

# PCB INSPECTION REPORT

Generated: October 28, 2025 at 21:25:53

## INSPECTION SUMMARY

<b>Metric</b>	<b>Value</b>
Total Defects Detected	5
Processing Time	1.23 seconds
Feature Matches Found	150
RANSAC Inliers	120
Alignment Quality	80.0%

## DEFECT DISTRIBUTION

<b>Defect Type</b>	<b>Count</b>	<b>Percentage</b>
no_defect	0	0.0%
solder_bridging	3	60.0%
component_missing	1	20.0%
misalignment	1	20.0%

## DETAILED DEFECT INFORMATION

### Defect #1

<b>Property</b>	<b>Value</b>
Defect Type	solder_bridging
Confidence Score	92.0%
Location (x, y)	(123, 456)
Defect Area	230 pixels <sup>2</sup>
Bounding Box	x:110, y:440, w:26, h:32

### Defect #2

<b>Property</b>	<b>Value</b>
Defect Type	component_missing
Confidence Score	88.0%
Location (x, y)	(50, 80)
Defect Area	180 pixels <sup>2</sup>
Bounding Box	x:40, y:70, w:20, h:30

### Defect #3

<b>Property</b>	<b>Value</b>
Defect Type	misalignment
Confidence Score	75.0%
Location (x, y)	(200, 120)
Defect Area	95 pixels <sup>2</sup>
Bounding Box	x:195, y:110, w:18, h:16

### Defect #4

<b>Property</b>	<b>Value</b>
Defect Type	solder_bridging
Confidence Score	67.0%
Location (x, y)	(300, 240)
Defect Area	120 pixels <sup>2</sup>
Bounding Box	x:295, y:235, w:12, h:18

## **Defect #5**

<b>&lt;b&gt;Property&lt;/b&gt;</b>	<b>&lt;b&gt;Value&lt;/b&gt;</b>
Defect Type	solder_bridging
Confidence Score	55.0%
Location (x, y)	(400, 320)
Defect Area	60 pixels <sup>2</sup>
Bounding Box	x:395, y:315, w:10, h:12

*Report generated by CircuitGuard-PCB System*